

MODEL: HSB31-212105 | **DESCRIPTION:** HEAT SINK

FEATURES

- BGA design
- low profile
- aluminum alloy
- black anodized finish



MODEL

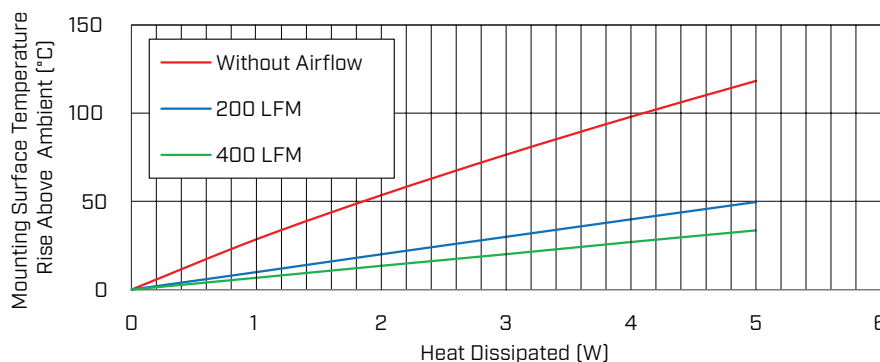
	thermal resistance ¹				power dissipation ¹ @ 75°C ΔT, nat conv [W]
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	@ 1 W, 400 LFM [°C/W]	
HSB31-212105	25.33	28.5	9.9	6.7	2.96

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power (W)	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	28.5	9.9	6.7
2	53.5	20.0	13.5
3	76.5	29.9	20.1
4	98.0	39.8	27.0
5	118.3	49.6	33.6

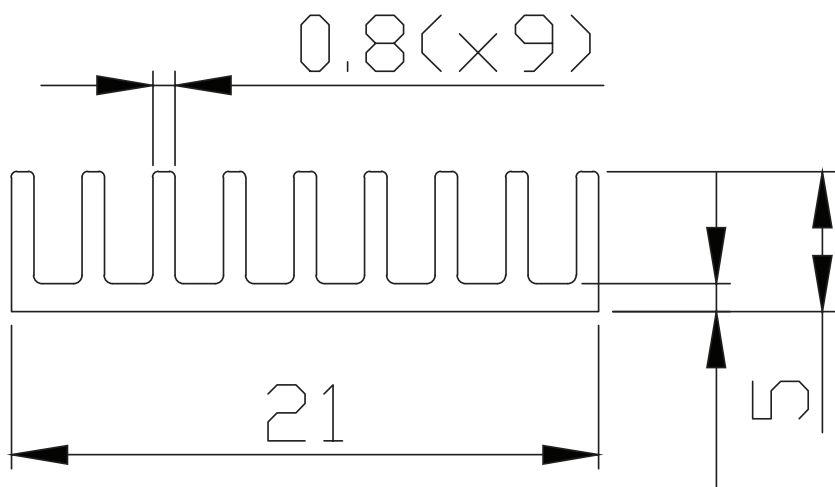
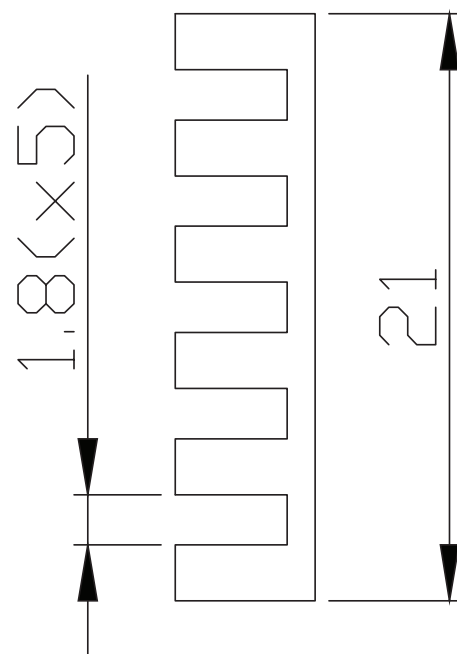
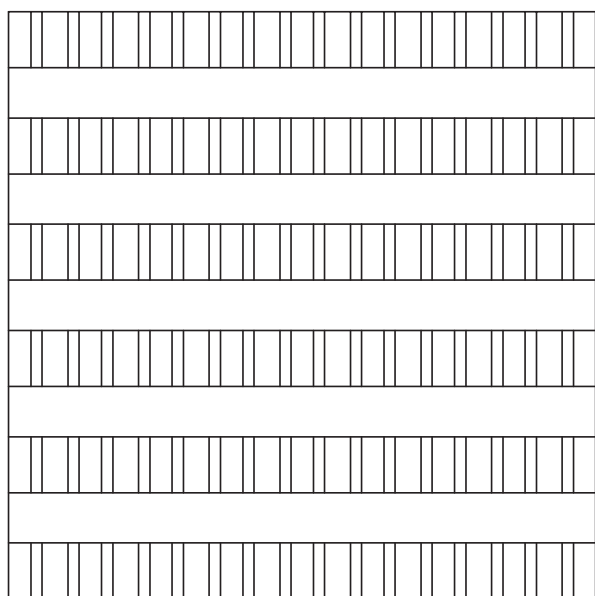
T_{hs}: "hot spot" temperature measured on the heatsink
T_a: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ±0.50 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	2 g



REVISION HISTORY

rev.	description	date
1.0	initial release	03/01/2024

The revision history provided is for informational purposes only and is believed to be accurate.



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